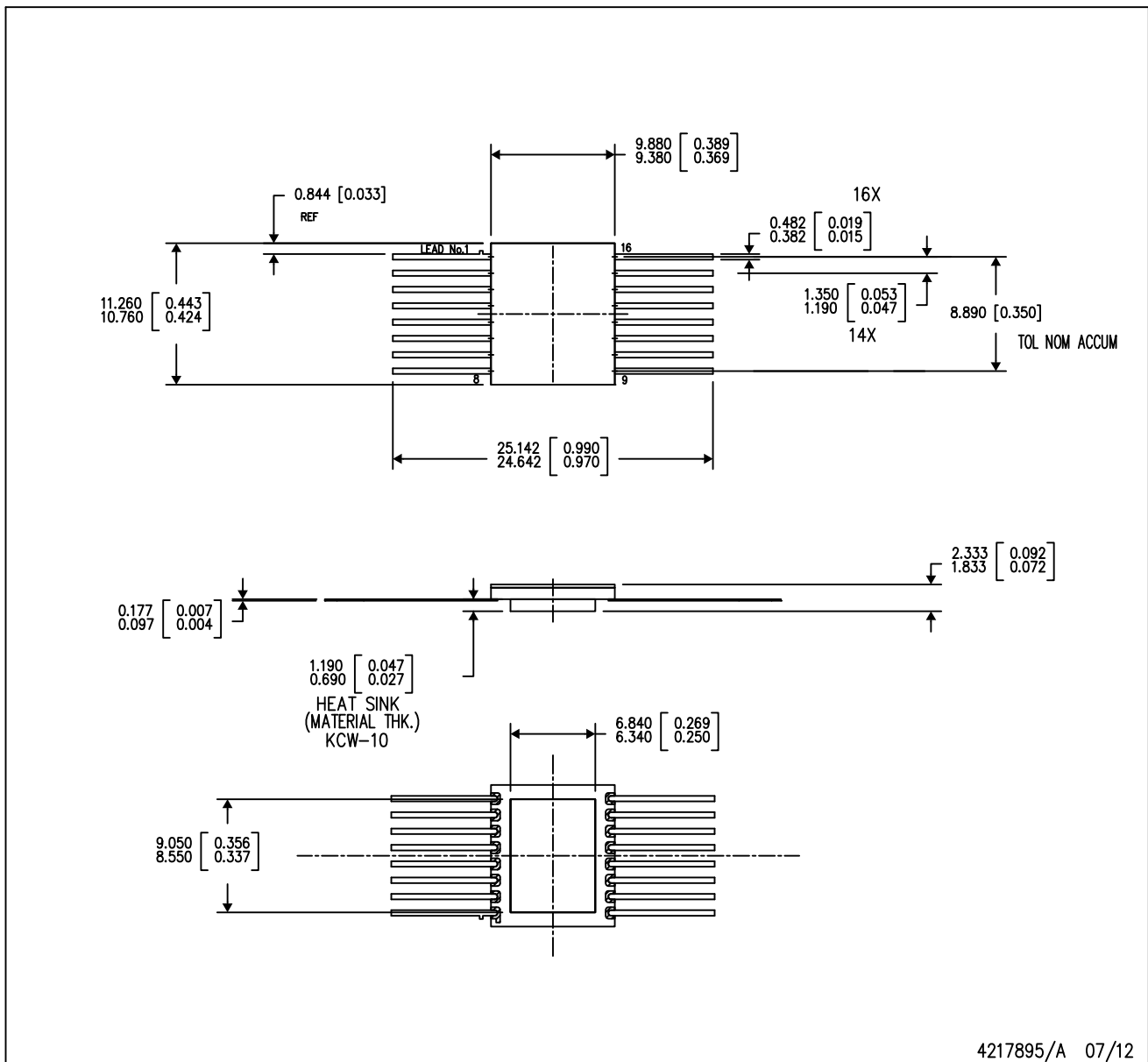


MECHANICAL DATA

HKR (R-CDFP-F16)

CERAMIC DUAL FLATPACK



- NOTES:
- All linear dimensions are in millimeters (inches).
 - This drawing is subject to change without notice.
 - This package is hermetically sealed with a metal lid. Lid and heat slug are connected to pin 8 (Gnd).
 - The terminals will be gold plated.

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